**[0006]** The problem to be solved by the present invention is as described above, and in order to solve this problem, a suction plate according to the present invention is a suction plate for holding an object to be cut having a substrate and a resin layer, the suction plate includes: a base member comprising a base part disposed on a base provided with a suction mechanism and a projection part formed to project upward from the base part and formed with a suction surface capable of sucking the resin layer; and a frame-like member disposed so as to surround a periphery of the projection part and including a mounting surface capable of mounting the substrate formed so as to be positioned above the suction surface. At least one of the base member and the frame-like member is formed with a discharge passage capable of discharging a foreign substance in a specified space defined by the projection part and the frame-like member to outside the specified space.

**[0007]** Further, the cutting device according to the present invention includes the suction plate and the base provided with the suction mechanism.

**[0008]** Further, the method for manufacturing an electronic component according to the present invention includes: a half cut process in which a half cut is performed on the object to be cut using the cutting device described above; and a full cut process in which a full cut is performed on the object to be cut that has been subjected to half cut in the half cut process, using the cutting device.

Effects of Invention

**[0009]** According to the present invention, a half-cut groove may be formed with high accuracy.

BRIEF DESCRIPTION OF THE DRAWINGS

**[0010]**

FIG. 1(a) is a bottom view showing a package substrate. (b) is a side view showing the package substrate.

FIG. 2 is a perspective view showing a semiconductor package in which a step part is formed.

FIG. 3 is a plan view schematically showing a configuration of the cutting device.

FIG. 4 is a side view schematically showing a configuration of the cutting device.

FIG. 5 is a block diagram showing an electrical connection relationship of the cutting device.

FIG. 6 is a side cross-sectional view showing a configuration of the table.

FIG. 7(a) is a plan view schematically showing a half-cut groove formed in the package substrate. (b) is a side view schematically showing the half-cut groove formed in the package substrate.

FIG. 8 is a flowchart showing a procedure of the half cut.

FIG. 9 is an exploded perspective view showing the suction plate.

FIG. 10 is a plan view showing the suction plate.

FIG. 11 is a plan view showing the base member.

FIG. 12 (a) is a diagram schematically showing a cross-section taken along line X1-X1 in FIG. 10. (b) is a diagram schematically showing a cross-section taken along line X2-X2 in FIG. 10.

FIG. 13 is a perspective view showing a path through which foreign substances are discharged in the suction plate.

FIG. 14 is a bottom view showing the base member.

FIG. 15(a) is a plan view showing the suction plate in which a chamfer part is formed. (b) is a plan view showing the suction plate according to a first modification example.

FIG. 16 is a plan view showing the suction plate according to a second modification example.